

ABSTRACT OF THE DISCLOSURE

An electrolytic polishing apparatus for electrolytic polishing a conductive film subject to formed on a substrate including a resistance measuring unit for measuring the resistance of the film.

- 5 The electrolytic polishing apparatus may also include a termination point detecting portion for detecting a termination point of polishing by reading a variation of the resistance value measured by the resistance measuring unit, or a polishing control portion for terminating electrolytic polishing on the basis of the
- 10 termination point of polishing detected by the termination point detecting portion.

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